

	Type	Hits	Search Text	DBs
9	BRS	2	"20040195703"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	BRS	3	substrate and die and bond adj pad and bond adj island and wire adj bond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	BRS	34	substrate and bond adj island	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
12	BRS	5	substrate and bond adj island and bond adj (pad pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	BRS	726	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
14	BRS	293	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated) and solder adj (ball balls)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	BRS	3	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated) and solder adj (ball balls) with redundant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
16	BRS	35	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated) and solder adj (ball balls) with (plate plating plated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors	Ref #
9	2005/05/03 17:11				S10
10	2005/10/07 16:33				S11
11	2005/10/07 16:33				S12
12	2005/10/07 16:34				S13
13	2005/10/07 16:35				S14
14	2005/10/07 16:36				S15
15	2005/10/07 16:36				S16
16	2005/10/07 16:37				S17

	Type	Hits	Search Text	DBs
17	BRS	7	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated) and solder adj (ball balls) near3 (plate plating plated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
18	BRS	3	substrate and die and bond adj pad and wire adj bond and solder adj (ball balls) near2 (plate plating plated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
19	BRS	15	substrate and die and bond adj pad and wire adj bond and solder adj (ball balls) near3 (plate plating plated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	BRS	17	substrate and die and bond adj pad and wire adj bond and solder adj (ball balls) near3 (coat coating coated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
21	BRS	1251	solder adj (ball balls) near3 (plate plating plated coat coating coated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
22	BRS	145	solder adj (ball balls) near3 (plate plating plated coat coating coated) with (connect connecting connected)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
23	BRS	39	solder adj (ball balls) near3 (plate plating plated coat coating coated) with (connect connecting connected) with (electric electrically)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
24	BRS	8	solder adj (ball balls) near3 (plate plating plated coat coating coated) with (connect connecting connected) with (electric electrically) and substrate and die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors	Ref #
17	2005/10/07 16:43				S18
18	2005/10/07 16:43				S20
19	2005/10/07 17:04				S19
20	2005/10/07 16:58				S21
21	2005/10/07 17:04				S22
22	2005/10/07 17:05				S23
23	2005/10/07 17:05				S24
24	2005/10/07 17:05				S25